



US 20220377900A1

(19) **United States**

(12) **Patent Application Publication**  
**MAYR**

(10) **Pub. No.: US 2022/0377900 A1**

(43) **Pub. Date: Nov. 24, 2022**

(54) **COMPONENT CARRIER WITH INDUCTIVE  
ELEMENT INCLUDED IN LAYER BUILD-UP,  
AND MANUFACTURING METHOD**

*H01F 27/28* (2006.01)

*H01F 27/32* (2006.01)

*H01F 41/04* (2006.01)

*H01F 41/12* (2006.01)

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(52) **U.S. Cl.**

CPC ..... *H05K 1/182* (2013.01); *H05K 1/115*  
(2013.01); *H05K 3/10* (2013.01); *H01F*

*27/2804* (2013.01); *H01F 27/323* (2013.01);

*H01F 41/041* (2013.01); *H01F 41/122*

(2013.01); *H05K 2201/08* (2013.01); *H05K*

*2201/1003* (2013.01); *H01F 2027/2809*

(2013.01)

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(21) Appl. No.: **17/663,965**

(22) Filed: **May 18, 2022**

**Related U.S. Application Data**

(60) Provisional application No. 63/189,762, filed on May  
18, 2021.

**Publication Classification**

(51) **Int. Cl.**

*H05K 1/18* (2006.01)

*H05K 1/11* (2006.01)

*H05K 3/10* (2006.01)

(57)

**ABSTRACT**

A component carrier includes a stack with at least one electrically insulating layer structure, a structured electrically conductive layer assembled to the stack, where a part of the structured electrically conductive layer is configured as an inductive element, and a magnetic matrix embedded in the stack. The magnetic matrix at least partially surrounds the inductive element. Further, a manufacturing method is described.

